

32/64-Mbit Flash Memory with 1.8 V I/O

< Outline >

In order to meet the needs of low voltage (1.8 V) CPUs and DSPs utilized in next generation mobile wireless phones, we have developed a 1.8 V I/O compliant boot block flash memory.

The use of conventional flash memory within next-generation mobile phone systems results in the need for a voltage level shifter and additional components, due to the usage of 2.7 V I/O. Our newly-developed 1.8 V I/O flash memory units allow for lowered chip counts in next-generation mobile wireless technology.

Also, further reductions in power consumption can be obtained through the use of our existing Auto Power Save mode. Data overwrite and delete functions can be disabled with the Block Lock and Block Lockdown features.

In addition, the incorporation of a 128-word OTP area allows for the permanent storage of passwords and ID codes.

Our current products include 8Mb and 16Mb flash memories. These new 32Mb and 64Mb flash memories will substantially enhance our product line.

< Main Specifications >

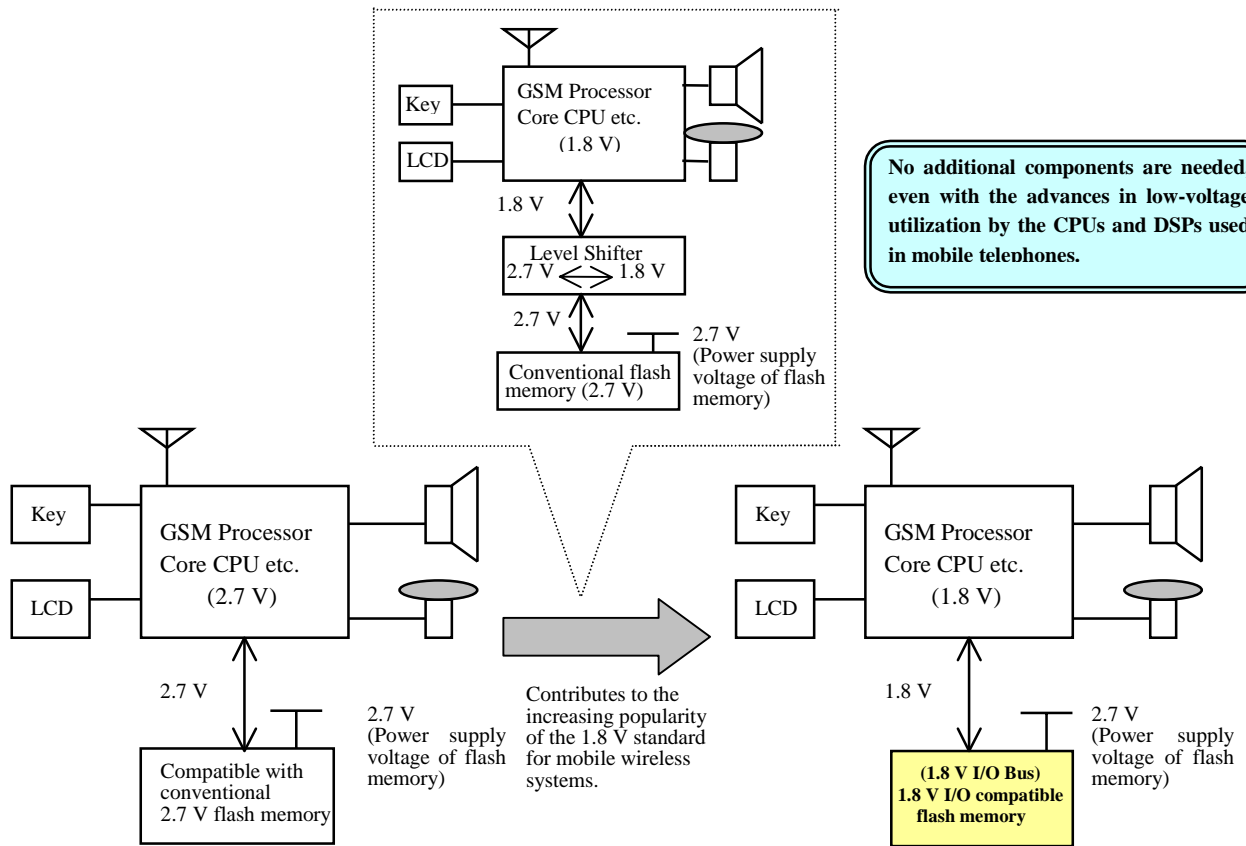
- Power supply voltage : $V_{CC} = 2.7$ to 3.6 V, $V_{PP} = 1.65$ to 3.6 V / 11.7 to 12.3 V, $V_{CCQ} = 1.65$ to 2.5 V / 2.7 to 3.6 V
- Access time (MAX.) :
 - <LH28F320BF(H)-PTTLF80/PBTLF80> : 80 ns ($V_{CC} = 2.7$ to 3.6 V, $V_{CCQ} = 1.65$ to 2.5 V)
 - <LH28F640BF(H)-PTTLF85/PBTLF85> : 85 ns ($V_{CC} = 2.7$ to 3.6 V, $V_{CCQ} = 1.65$ to 2.5 V)
- Page mode access time (MAX.) : 25 ns ($V_{CCQ} = 2.7$ to 3.6 V)
40 ns ($V_{CCQ} = 1.65$ to 2.5 V)
- Read current : 15 mA (TYP.), 25 mA (MAX.)
- Standby current : TBD
- Operating temperature range :
 - <LH28F320BF-PTTLF80/PBTLF80, LH28F640BF-PTTLF85/PBTLF85> : 0 to 70C
 - <LH28F320BFH-PTTLF80/PBTLF80, LH28F640BFH-PTTLF85/PBTLF85> : - 40 to 85C
- Data rewriting : 100 000 times / block
- Package :
 - <LH28F320BF(H)E-PTTLF80/PBTLF80> : 48TSOP(1)(P-TSOP048-1220)
 - <LH28F320BF(H)B-PTTLF80/PBTLF80> : 48FBGA(CSP)(T(R)-TFBGA048-0808)
 - <LH28F640BF(H)E-PTTLF85/PBTLF85> : 48TSOP(1)(P-TSOP048-1220)
 - <LH28F640BF(H)B-PTTLF85/PBTLF85> : 60FBGA(CSP)(T(R)-TFBGA060/048-0811)

< 32/64-Mbit Flash Memory with 1.8 V I/O >

* Under development

Supply voltage		Smart3		Supply voltage can be selected automatically from the following combinations; V _{CC} = 2.7 to 3.6 V, V _{PP} = 1.65 to 3.6 V / V _{CC} = 2.7 to 3.6 V, V _{PP} = 11.7 to 12.3 V								
Capac- ity	Bit con- fig- ura- tion	Erasable Block size		Model No.	Access time (ns)MAX.		Page mode access time (ns)MAX,		Read current (mA) MAX. f=5 MHz (CMOS)	Standby current (u) MAX. (CMOS)	Oper- ating temp. (C)	Package
					(V _{CCQ} = 2.7 to 3.6 V)	(V _{CCQ} = 1.65 to 2.5 V)	(V _{CCQ} = 2.7 to 3.6 V)	(V _{CCQ} = 1.65 to 2.5 V)				
32M	X16	Para- Meter : 4Kword X8 Main : 32Kword X63	Top boot	*LH28F320BFE/B -PTTLF80	60	80	25	25	25	TBD	0 to 70	P-TSOP048 -1220 T(R)-TFBGA 048-0808
			Top boot	*LH28F320BFHE/B -PTTLF80	60	80	25	25	25	TBD	-40 to 85	P-TSOP048 -1220 T(R)-TFBGA 048-0808
		Bot- tom boot	*LH28F320BFE/B -PBTLF80	60	80	25	25	25	TBD	0 to 70	P-TSOP048 -1220 T(R)-TFBGA 048-0808	
			*LH28F320BFHE/B -PBTLF80	60	80	25	25	25	TBD	-40 to 85	P-TSOP048 -1220 T(R)-TFBGA 048-0808	
64M	X16	Para- Meter : 4Kword X8 Main : 32Kword X127	Top boot	*LH28F640BFE/B -PTTLF85	65	85	25	25	25	TBD	0 to 70	P-TSOP048 -1220 T(R)-TFBGA 060/048-0811
			Top boot	*LH28F640BFHE/B -PTTLF85	65	85	25	25	25	TBD	-40 to 85	P-TSOP048 -1220 T(R)-TFBGA 060/048-0811
		Bot- tom boot	*LH28F640BFE/B -PBTLF85	65	85	25	25	25	TBD	0 to 70	P-TSOP048 -1220 T(R)-TFBGA 060/048-0811	
			*LH28F640BFHE/B -PBTLF85	65	85	25	25	25	TBD	-40 to 85	P-TSOP048 -1220 T(R)-TFBGA 060/048-0811	

< Advantages of Applications >



Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. Manufacturing locations are also subject to change without notice. In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that occur in equipment using any SHARP devices shown in catalogs, data books, etc.

The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property right. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP devices.

SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structures and other contents described herein at any time without notice in order to improve design or reliability.